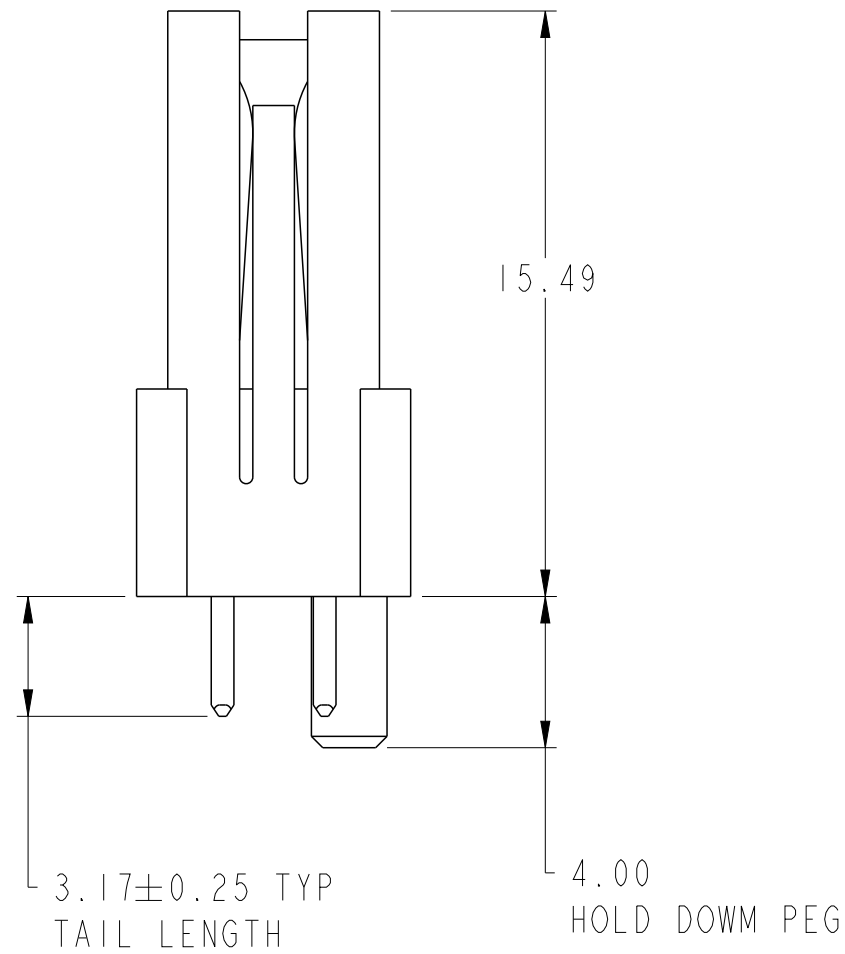
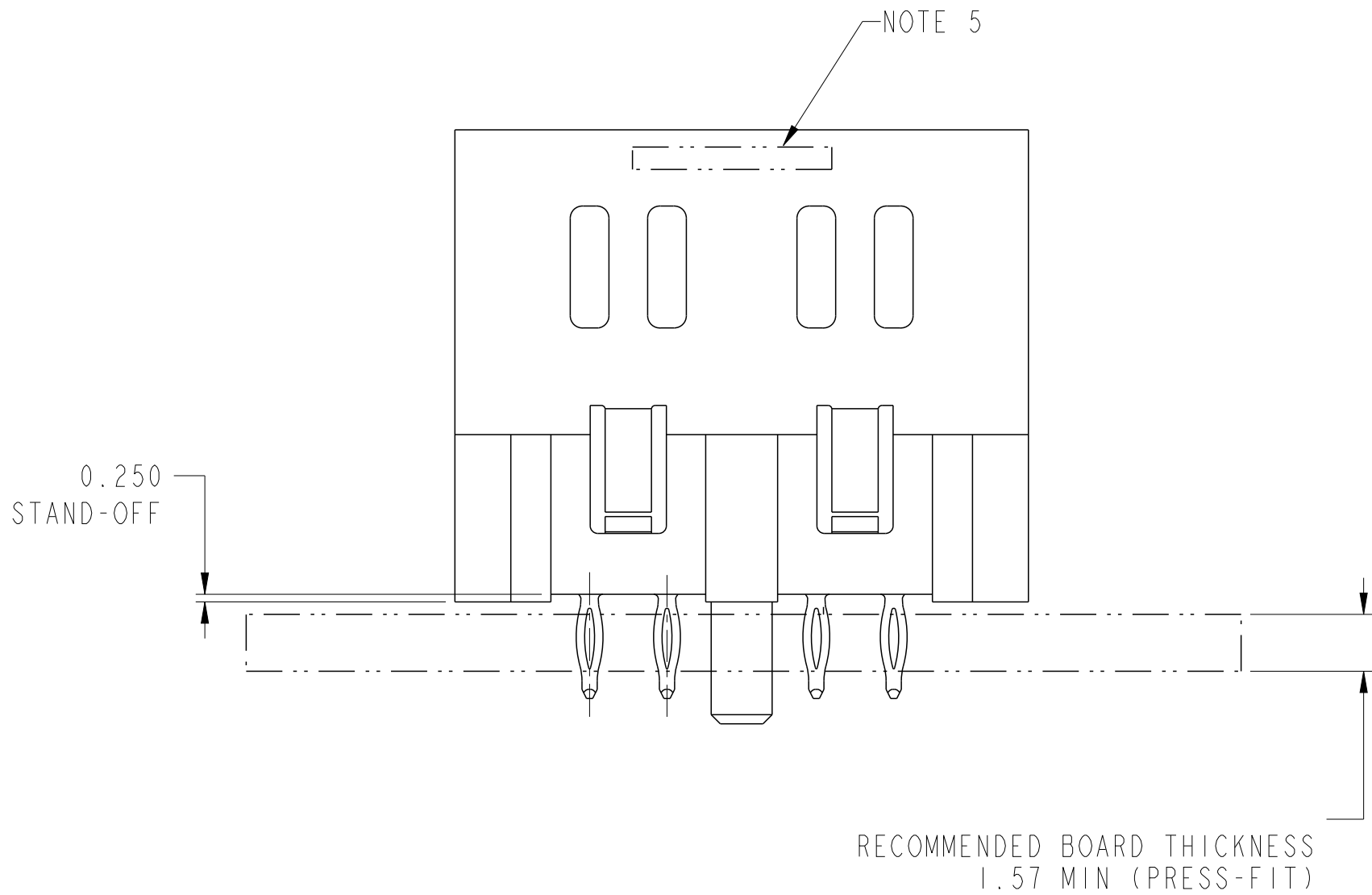
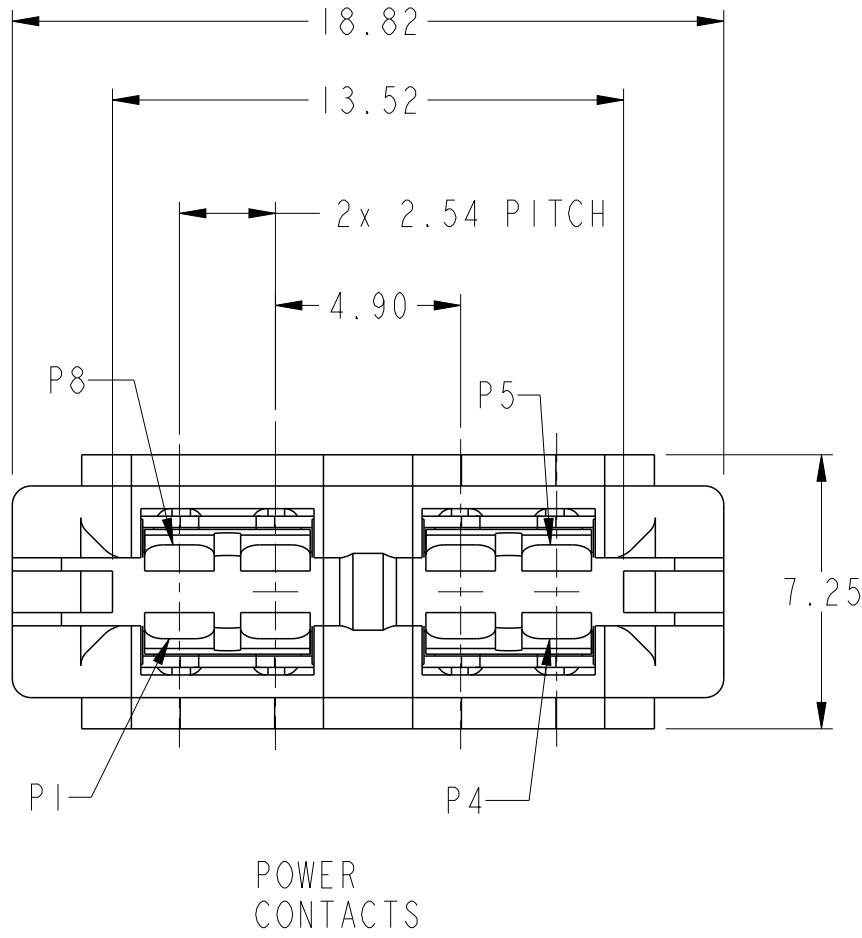
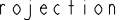
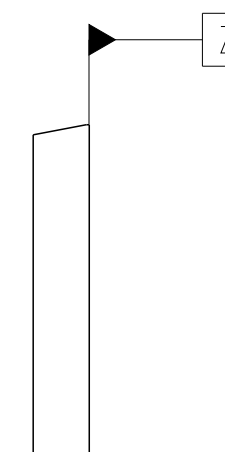


1	2
PART NUMBER	TAIL TYPE
10136109-001LF	PRESS FIT
10136109-002LF	SOLDER TAIL



spec ref		-		dr	Hai-Ling Liu	2015/07/09	projection		mm	size	A2	scale	5:1	
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng	Sunny2 Liu	2016/06/07					ecn no		ELX-DG-24234-1	
ISO 406				chr	Terris Liu	2016/06/16	product family		CARD EDGE	rel level	Released			
ISO 1101				appr	Pei-Ming Zheng	2016/06/16								
surface	linear	0.X	±0.5	Amphenol FCI	title	HPCE MEZZANINE 4LP WITH PEG				dwg no	10136109		rev	C
		0.XX	±0.25											
		0.XXX	±0.10											
ASME Y14.5	angular	0°	±2°		cat. no.	-	Product - Customer Drw				sheet 1 of 3			

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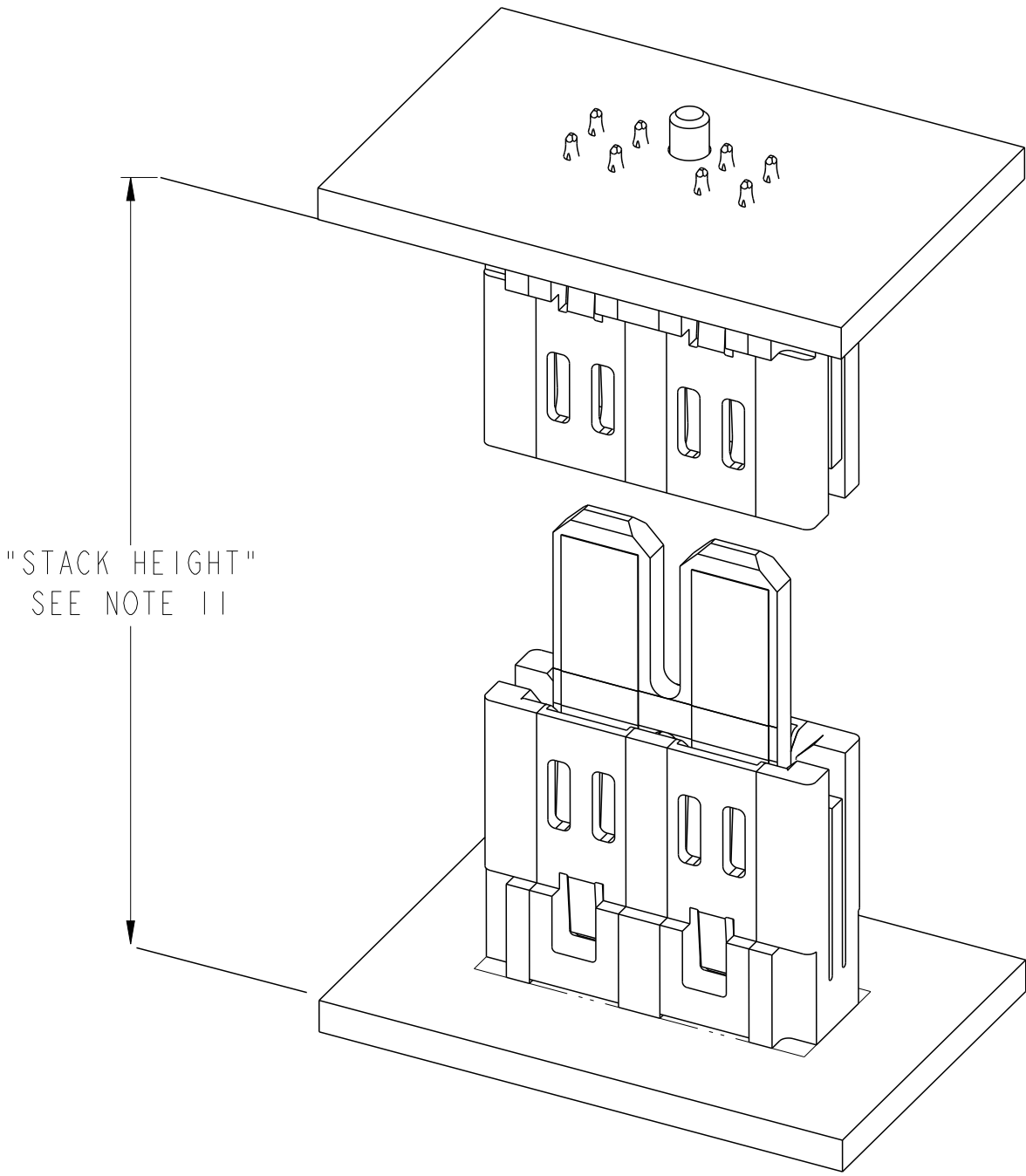
PDS: Rev :C

STATUS⁷:Released

Printed: Jun 16, 2016

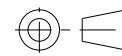
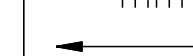
CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE 1 (HPCE / PRESS-FIT TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
POWER	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.65 - 0.80
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.70 - 0.80
	COPPER (SEE NOTE 8)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	0.70 - 0.80

CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE 1 (HPCE / SOLDER TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
POWER	TIN-LEAD	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.94 - 1.10
	IMMERSION TIN	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.94 - 1.10
	COPPER (SEE NOTE 8)	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	--	0.94 - 1.10



NOTES:

1. CONNECTOR MATERIALS:
- HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, BLACK
UL 94V-0 COMPLIANT
- CONTACTS: HIGH PERFORMANCE COPPER ALLOY.
2. CONTACT FINISH REF. GS-12-1261 SECTION 5.3.
3. PRODUCT SPECIFICATION: GS-12-1261.
4. APPLICATION SPECIFICATION: GS-20-128.
5. PRODUCT MARKING ON HOUSING IN AREA SHOWN SHOULD MEET AFCI SPECIFICATION GS-24-007..
6. PACKAGING MEETS FCI SPECIFICATION GS-14-937.
7. HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
8. COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
9. ALL HOLE SIZES ARE FINISHED HOLE SIZES.
10. INTENDED USE: TWO ASSEMBLIES (P/N 10134991 MATE TO 10136109) MEZZANINE STACKED USING PCB TO CONTROL STACK HEIGHT.
DIM "L" + 10.98mm = FINAL MEZZANINE STACK HEIGHT.
DIM "L" RANGES FROM 21.02-46.62 mm .
11. SEE DRAWING 10135823 FOR MATING PCB DETAIL
12. A SYMBOL  WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.

spec ref -		dr		Hai-Ling Liu	2015/07/09			size	A2	scale	1:1	
tolerance std		eng		Sunny2 Liu	2016/06/07			ecn no	ELX-DG-24234-1	rel level	Released	
ISO 406		chr		Terris Liu	2016/06/16							
ISO 1101		appr		Pei-Ming Zheng	2016/06/16							
				product family				-				
surface		linear	0.X	±0.5	Amphenol FCI	HPCE MEZZANINE		dwg no	10136109		rev	C
ASME Y14.5			0.XX	±0.25								
			0.XXX	±0.10								
		angular	0°	±2°	cat. no.		-	Product - Customer Drw		sheet 3 of 3		